

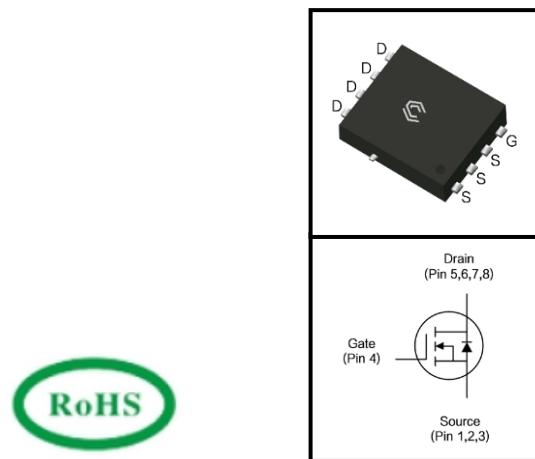
40V N-Channel MOSFET

FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent C*dV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Load Switching
- Hard switched and high frequency circuits
- Uninterruptible power supply



Device Marking and Package Information

Device	Package	Marking
CSN04N2P1	PDFN5x6	CSN04N2P1

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	40	V
Continuous Drain Current	I_D	160	A
Pulsed Drain Current (note1)	I_{DM}	640	A
Gate-Source Voltage	V_{GSS}	± 20	V
Single Pulse Avalanche Energy (note2)	E_{AS}	198.8	mJ
Avalanche Current (note1)	I_{AS}	23.4	A
Repetitive Avalanche Energy (note1)	E_{AR}	0.8	mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	108.3	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	°C

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note3)	R_{thJC}	1.15	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5	

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$	40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 40\text{V}$, $V_{\text{GS}} = 0\text{V}$, $T_J = 25^\circ\text{C}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$	1.0	--	2.5	V
Drain-Source On-Resistance (note4)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}$, $I_D = 20\text{A}$	--	1.6	2.1	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}$, $I_D = 15\text{A}$	--	2.2	2.8	$\text{m}\Omega$
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}$, $V_{\text{DS}} = 20\text{V}$, $f = 1.0\text{MHz}$	--	3403	--	pF
Output Capacitance	C_{oss}		--	1683	--	
Reverse Transfer Capacitance	C_{rss}		--	114	--	
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}$, $f = 1\text{ MHz}$	--	2.00	--	Ω
Total Gate Charge	Q_g	$V_{\text{DD}} = 32\text{V}$, $I_D = 50\text{A}$, $V_{\text{GS}} = 10\text{V}$	--	60.9	--	nC
Gate-Source Charge	Q_{gs}		--	5.4	--	
Gate-Drain Charge	Q_{gd}		--	9.0	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 20\text{V}$, $I_D = 50\text{A}$, $R_G = 3.1\Omega$	--	13	--	ns
Turn-on Rise Time	t_r		--	35	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	48	--	
Turn-off Fall Time	t_f		--	20	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	160	A
Pulsed Diode Forward Current	I_{SM}		--	--	640	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}$, $I_{\text{SD}} = 20\text{A}$, $V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Time	t_{rr}	$V_{\text{DD}} = 20\text{V}$, $I_S = 50\text{A}$, $di_f/dt = 100\text{A}/\mu\text{s}$	--	61	--	ns
Reverse Recovery Charge	Q_{rr}		--	0.027	--	μC

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L=0.5\text{mH}$, $V_{\text{DD}} = 20\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. Reference standard for thermal resistance testing: JESD51-14
4. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

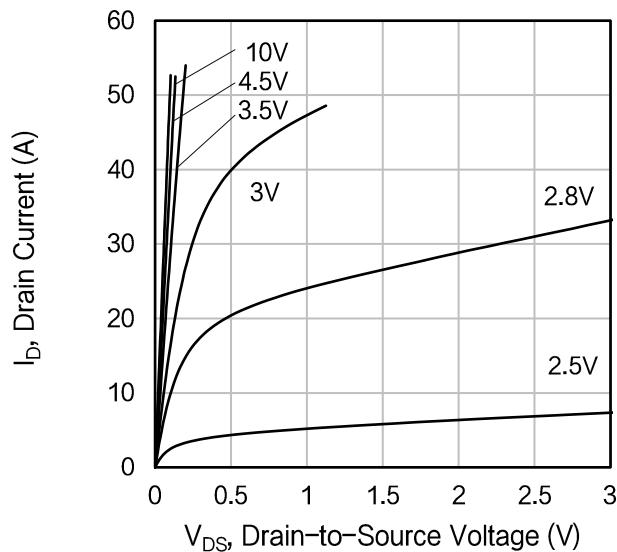


Figure 2. Body Diode Forward Voltage

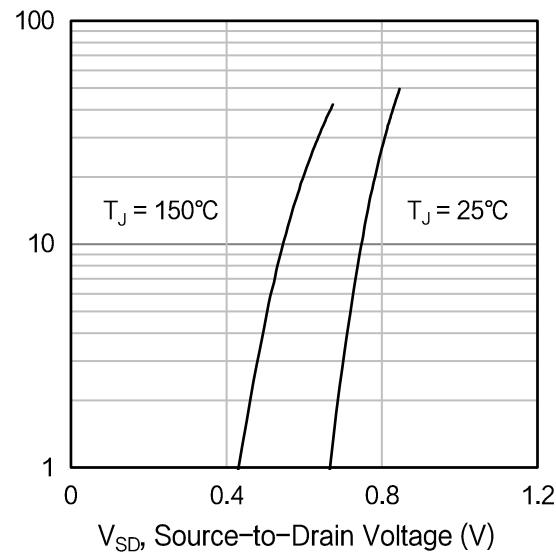


Figure 3. Drain Current vs. Temperature

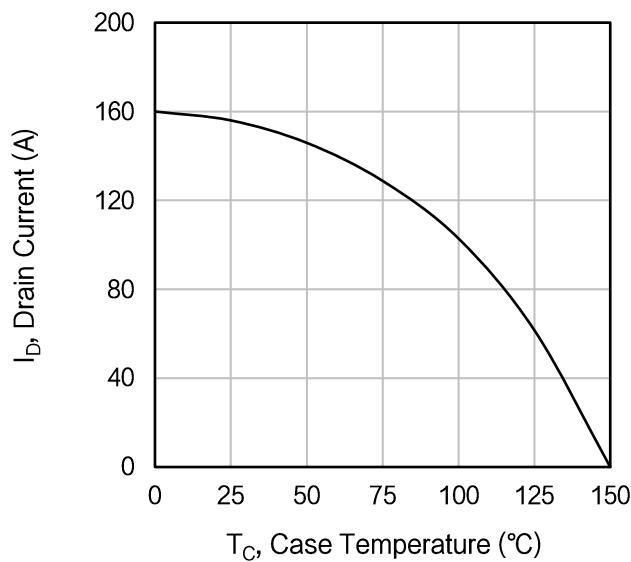


Figure 4. BV_{DSS} Variation vs. Temperature

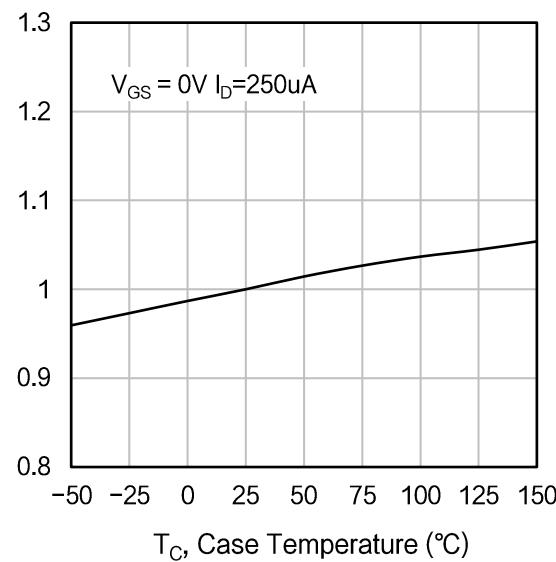


Figure 5. Transfer Characteristics

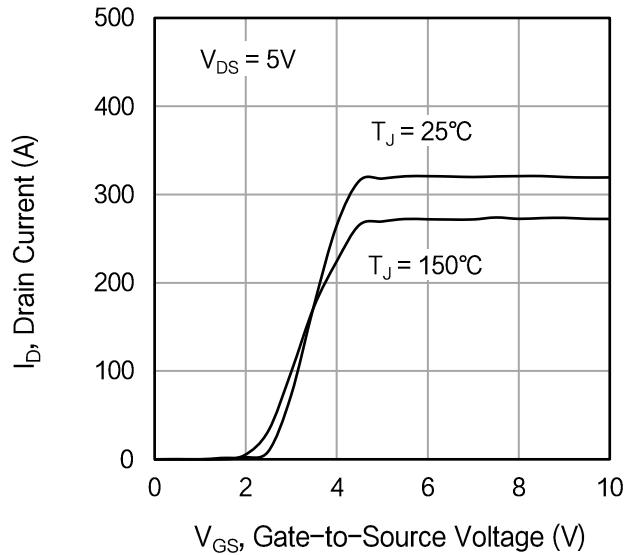
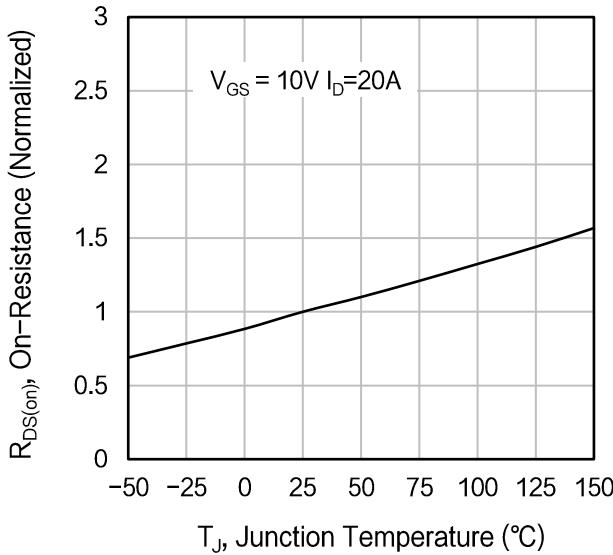


Figure 6. On-Resistance vs. Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Fig.7 Threshold Voltage vs. Temperature

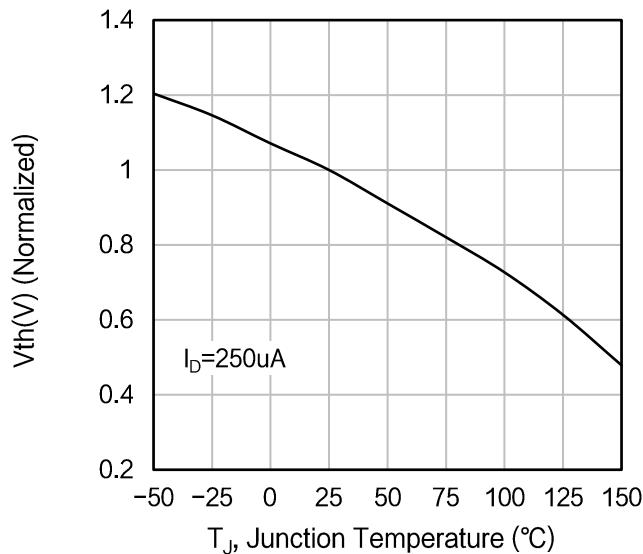


Figure 8. On-Resistance vs. Drain Current

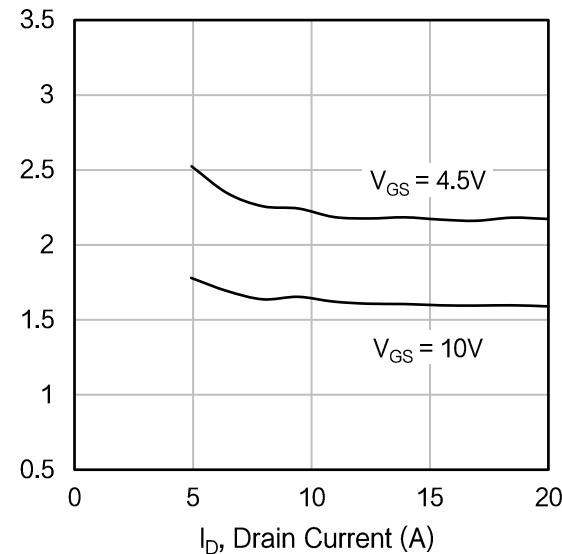


Figure 9. Capacitance

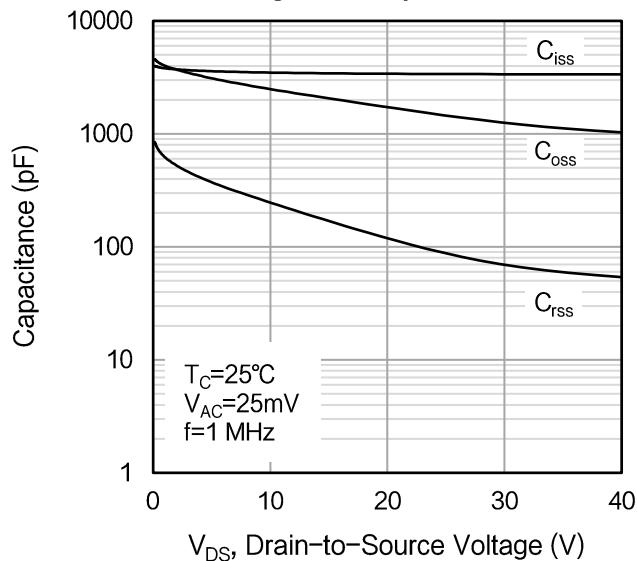


Figure 10. Gate Charge

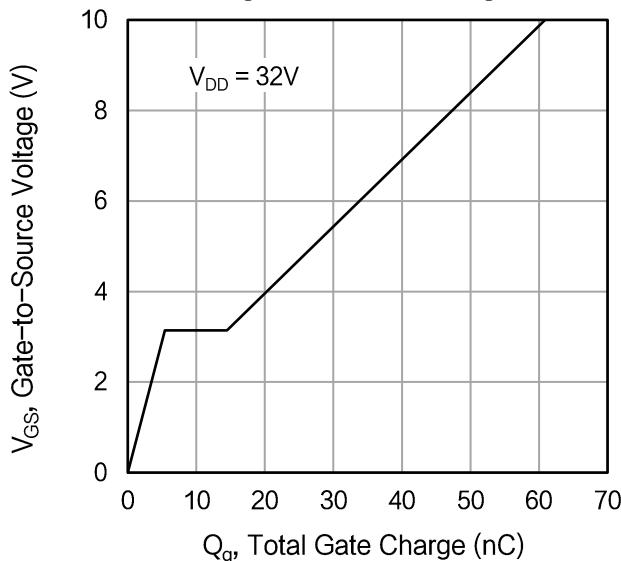


Figure 11. Safe Operating Area

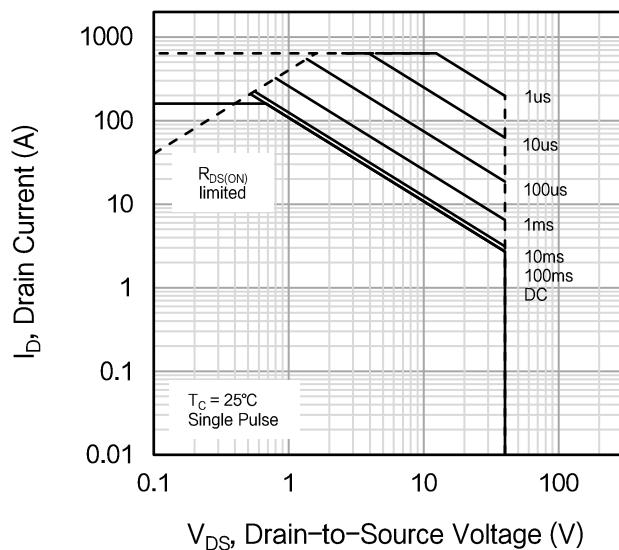
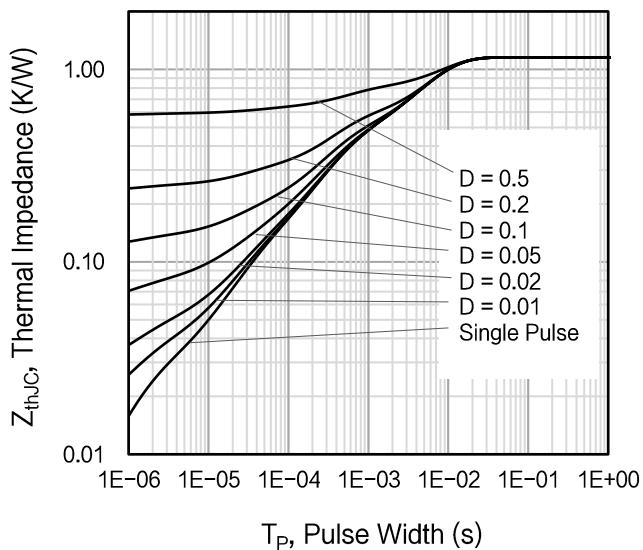


Figure 12. Transient Thermal Impedance



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Fig.13 D-S Leakage Current vs. D-S Voltage

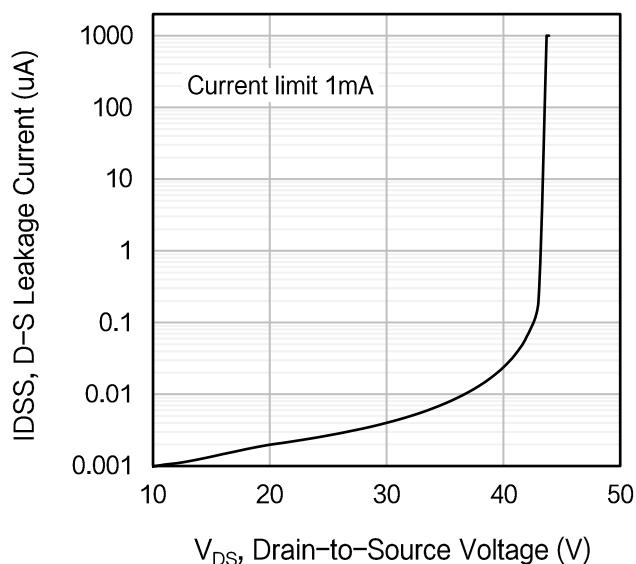


Figure 14. G-S Leakage Current vs. G-S Voltage

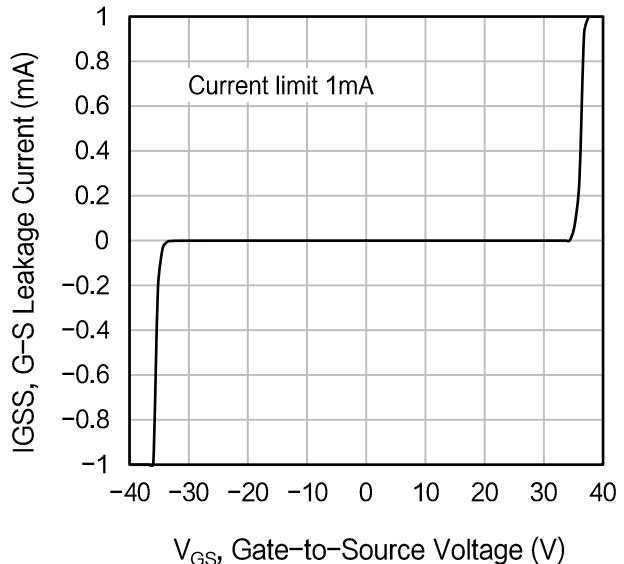


Figure A: Gate Charge Test Circuit and Waveform

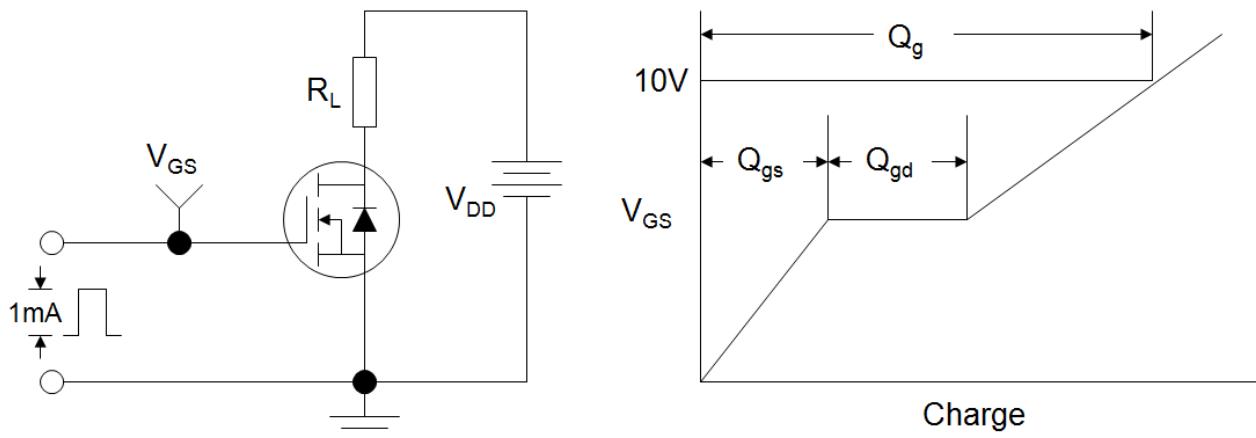


Figure B: Resistive Switching Test Circuit and Waveform

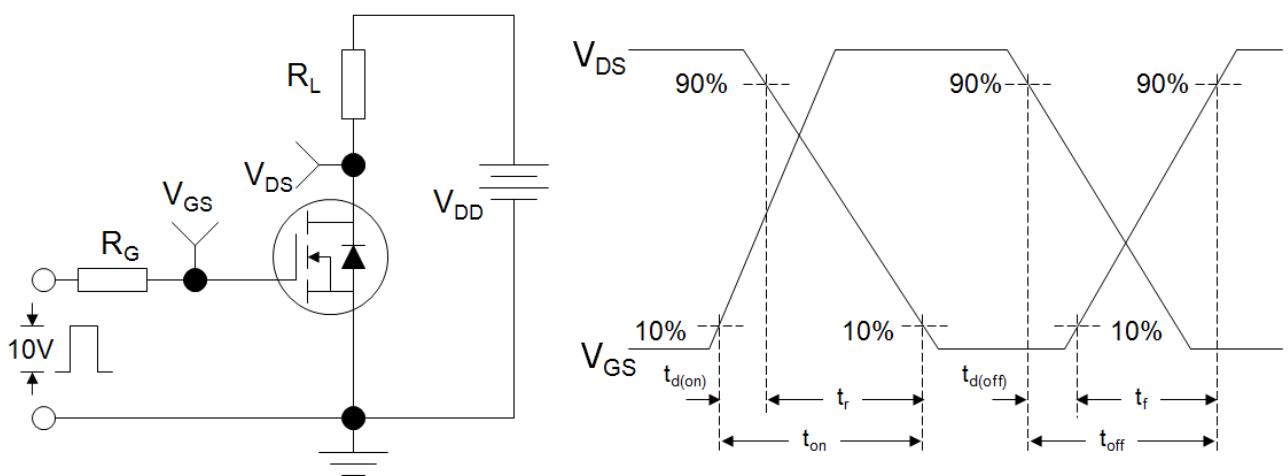
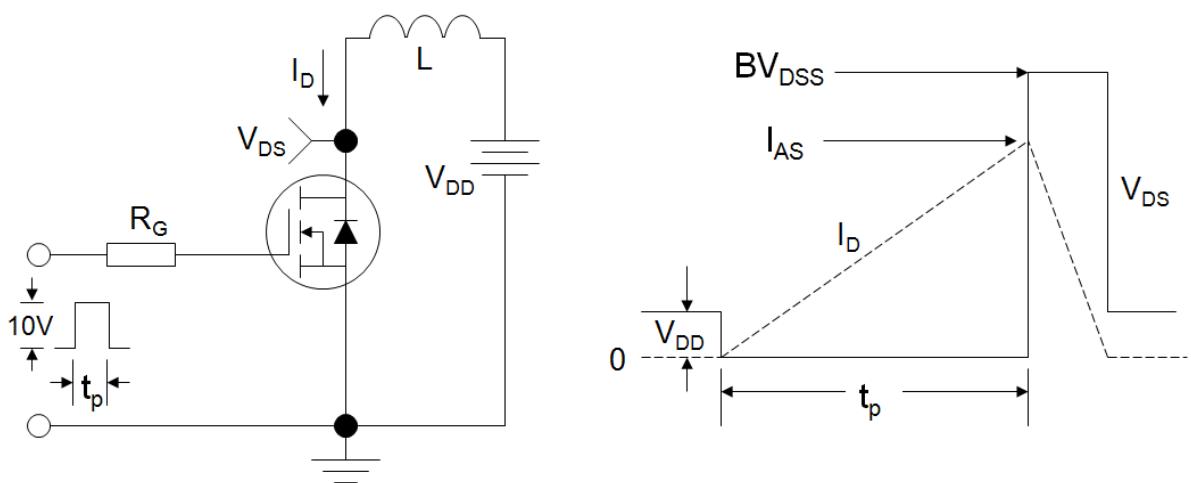
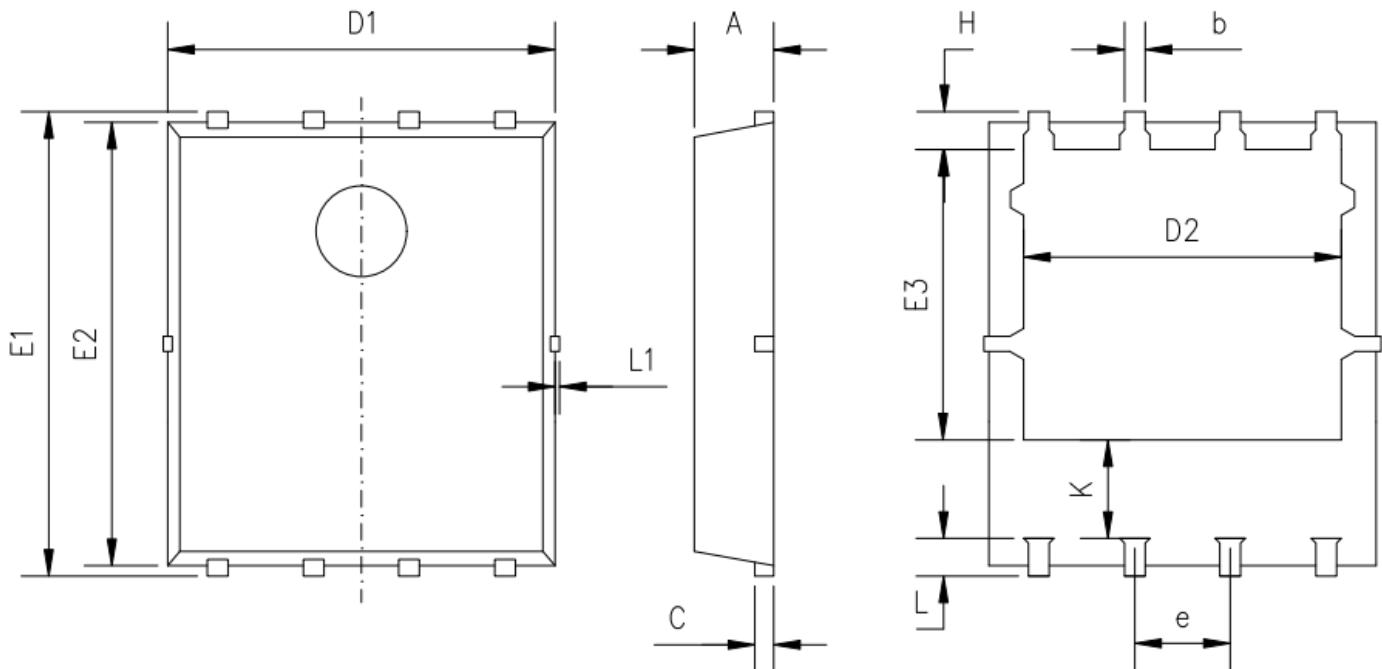


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



PDFN5 × 6



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	0.90	1.20
b	0.25	0.50
C	0.10	0.35
D1	4.80	5.40
D2	3.72	4.25
e	1.17	1.37
E1	5.90	6.35
E2	5.60	6.06
E3	3.33	3.92
H	0.40	0.71
L	0.30	0.84
L1	0.00	0.15
K	1.00	1.50

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